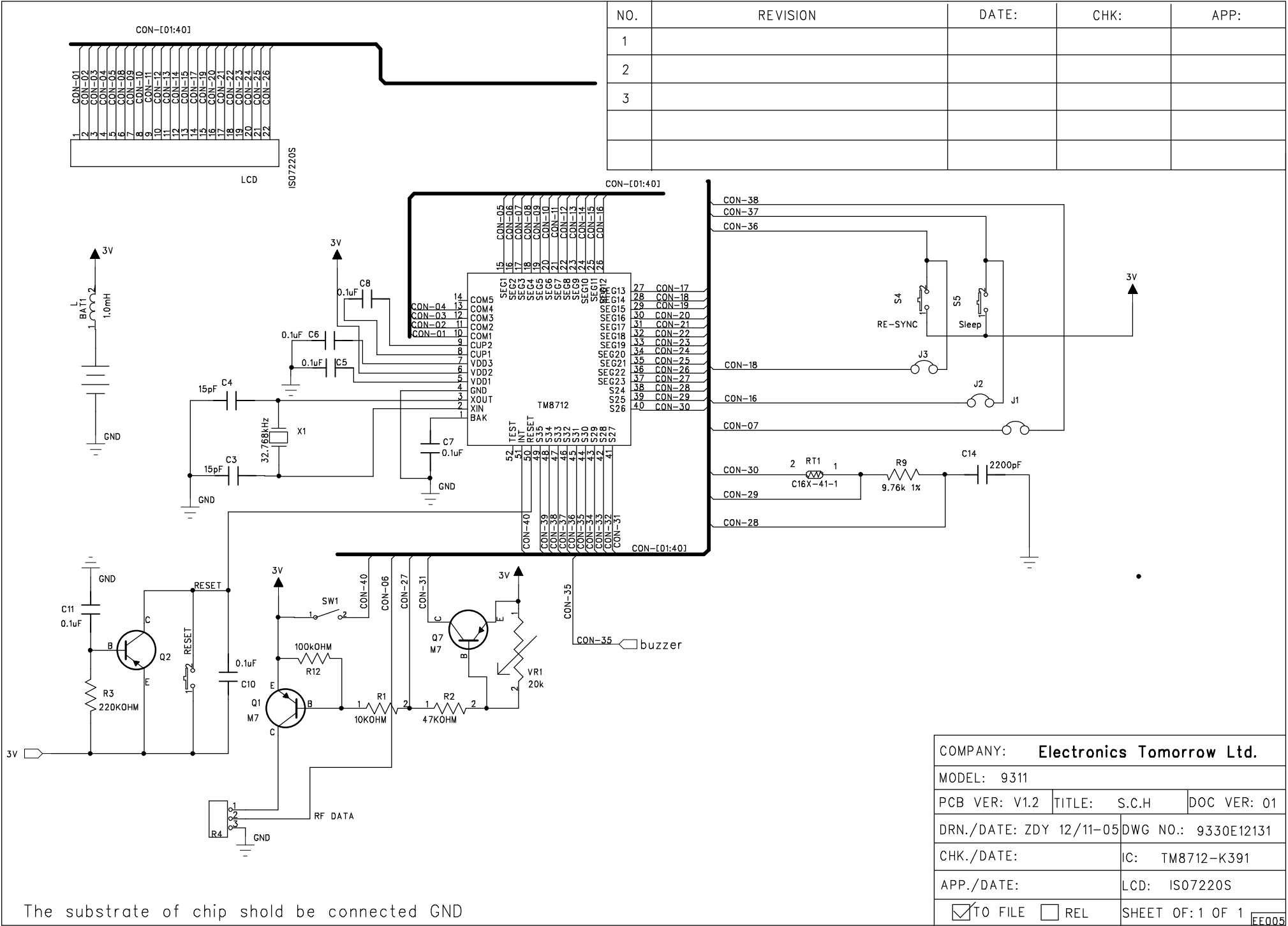
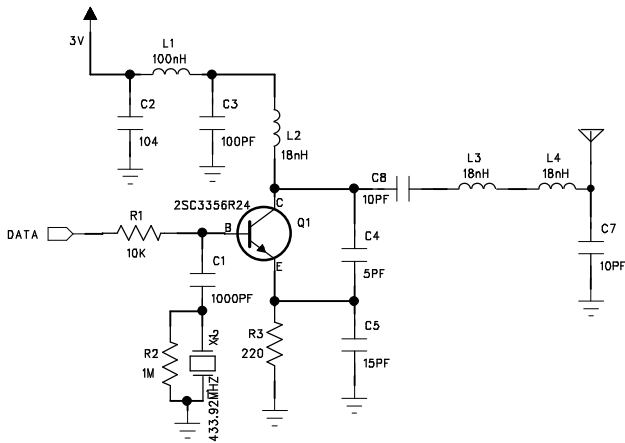




The substrate of chip shold be connected GND

NO.	REVISIONS:	DATE:	CHK:	APP:



COMPANY: Electronics Tomorrow Ltd.			
MODEL: 9311-----RF			
PCB VER:V1.0	TITLE: S C H	DOC VER: 00	
DRN./DATE: L.F 18/3-05	DWG NO: 7066E10231		
CHK./DATE:	IC:		
APP./DATE:	LCD:		
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